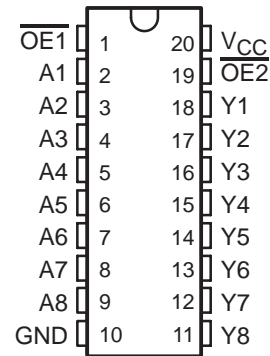


SN64BCT541A OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCBS031B – FEBRUARY 1989 – REVISED SEPTEMBER 1994

- BiCMOS Design Significantly Reduces Standby Current
- 3-State True Outputs Drive Bus Lines or Buffer Memory-Address Registers
- High-Impedance State During Power Up and Power Down
- P-N-P Inputs Reduce DC Loading
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

DW OR N PACKAGE
(TOP VIEW)



description

The SN64BCT541A octal buffer and line driver is ideal for driving bus lines or buffering memory-address registers. The device features inputs and outputs on opposite sides of the package to facilitate printed-circuit-board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state. The outputs are in a high-impedance state during power up and power down while the supply voltage is less than approximately 3 V.

The SN64BCT541A is characterized for operation from -40°C to 85°C and from 0°C to 70°C .

FUNCTION TABLE

INPUTS			OUTPUT Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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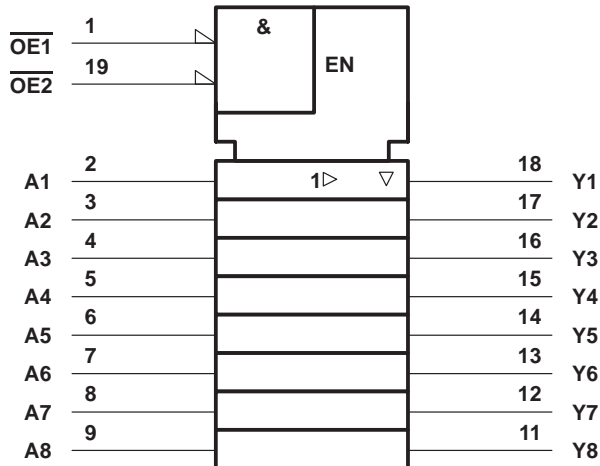
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OCTAL BUFFER/DRIVER

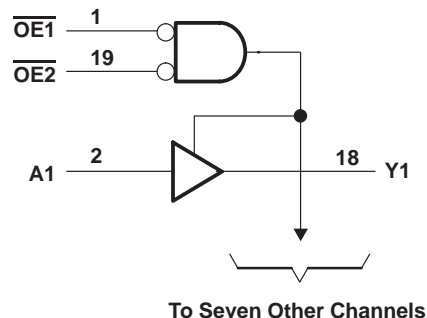
WITH 3-STATE OUTPUTS

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logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O	–0.5 V to V_{CC}
Current into any output in the low state	128 mA
Operating free-air temperature range, T_A	–40°C to 85°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input negative voltage rating may be exceeded if the input clamp current rating is observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High-level output current			–15	mA
I_{OL}	Low-level output current			64	mA
T_A	Operating free-air temperature	–40		85	°C



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SN64BCT541A

OCTAL BUFFER/DRIVER

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.3		V
		$I_{OH} = -15\text{ mA}$	2	3.1		
V_{OL}	$V_{CC} = 4.5\text{ V}$,	$I_{OH} = 64\text{ mA}$		0.42	0.55	V
I_{OZH}	$V_{CC} = 5.5\text{ V}$,	$V_O = 2.7\text{ V}$			50	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$,	$V_O = 0.5\text{ V}$			-50	μA
I_{OZ}	$V_{CC} = 0\text{ to }2.3\text{ V}$ (power up)	$V_O = 2.7\text{ V or }0.5\text{ V}$, \overline{OE} at 0.8 V			± 50	μA
	$V_{CC} = 1.8\text{ V to }0$ (power down)				± 50	
I_I	$V_{CC} = 5.5\text{ V}$,	$V_I = 7\text{ V}$			0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$,	$V_I = 2.7\text{ V}$			20	μA
I_{IL}	$V_{CC} = 5.5\text{ V}$,	$V_I = 0.5\text{ V}$			-0.6	mA
I_{OS}^\ddagger	$V_{CC} = 5.5\text{ V}$,	$V_O = 0$	-100		-225	mA
I_{CCL}	$V_{CC} = 5.5\text{ V}$			47	72	mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$			27	40	mA
I_{CCZ}	$V_{CC} = 5.5\text{ V}$			5	7	mA
C_i	$V_{CC} = 5\text{ V}$,	$V_I = 2.5\text{ V or }0.5\text{ V}$		5		pF
C_o	$V_{CC} = 5\text{ V}$,	$V_O = 2.5\text{ V or }0.5\text{ V}$		10		pF

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T _A = 25°C			V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω				UNIT
						T _A = −40°C to 85°C		T _A = 0°C to 70°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	2.1	3.7	5.3	1.7	6.3	1.7	6	ns
t _{PHL}			3.7	5.5	7.5	3.2	8.7	3.4	8.2	
t _{PZH}	$\overline{\text{OE}}$	Y	4.5	7.2	9.3	4.4	11	3.9	10.7	ns
t _{PZL}			5	8	10.4	5.4	12.4	4.4	11.5	
t _{PHZ}	$\overline{\text{OE}}$	Y	3.5	5.6	7.6	3	9.1	3	8.6	ns
t _{PLZ}			3.9	5.2	7.2	3	9.4	3	8.6	



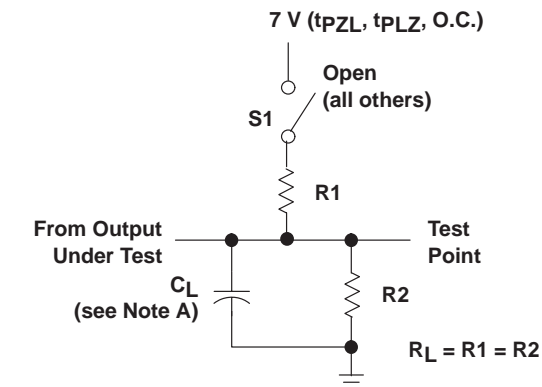
SN64BCT541A

OCTAL BUFFER/DRIVER

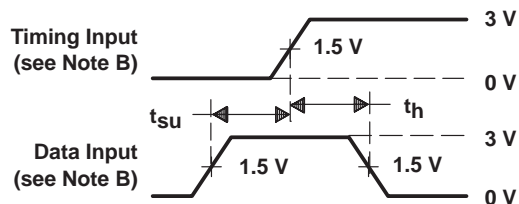
WITH 3-STATE OUTPUTS

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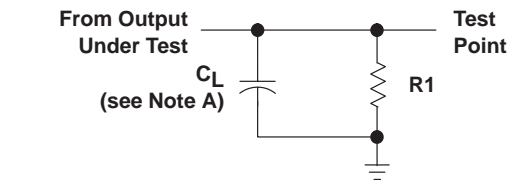
PARAMETER MEASUREMENT INFORMATION



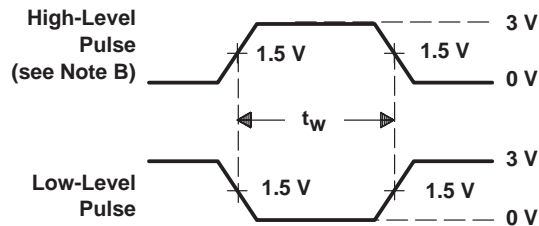
LOAD CIRCUIT FOR 3-STATE AND OPEN-COLLECTOR OUTPUTS



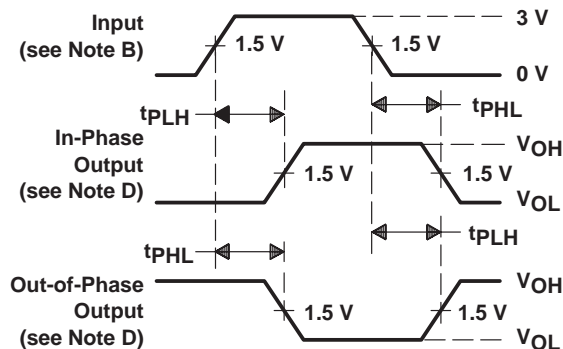
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



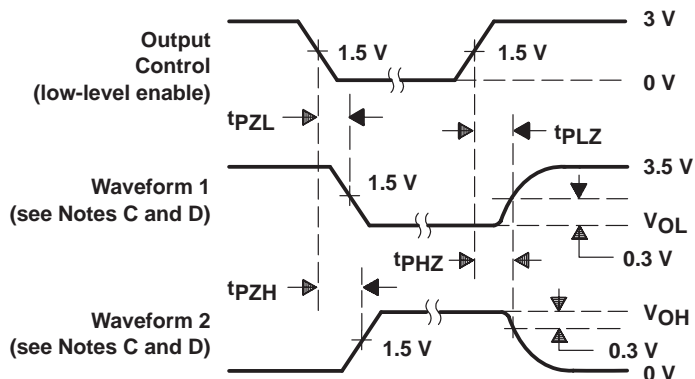
LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS



VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES (see Note D)



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES:
- C_L includes probe and jig capacitance.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - The outputs are measured one at a time with one transition per measurement.
 - When measuring propagation delay times of 3-state outputs, switch S1 is open.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN64BCT541ADW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN64BCT541ADWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN64BCT541AN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A**PACKAGE OUTLINE****SOIC - 2.65 mm max height**

SOIC



4220724/A 05/2016

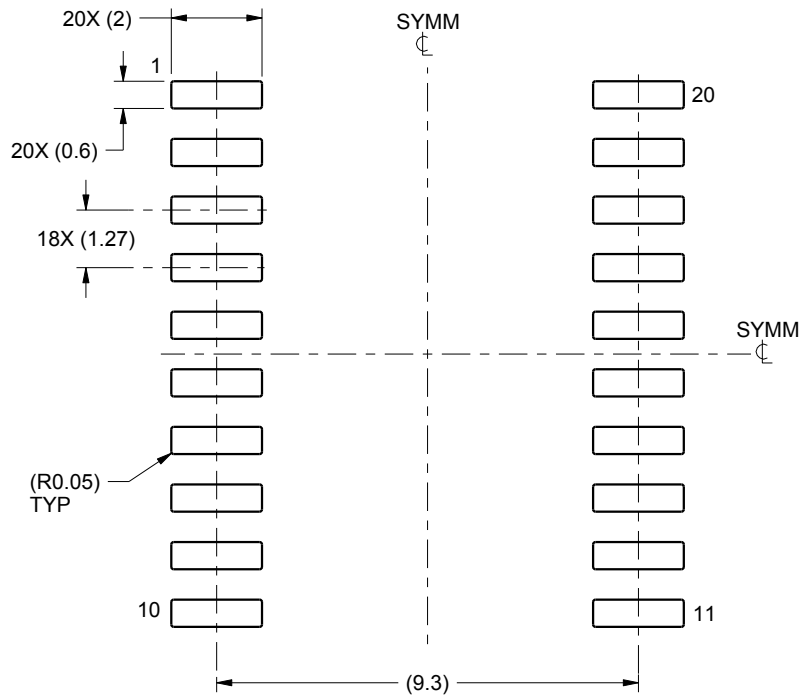
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

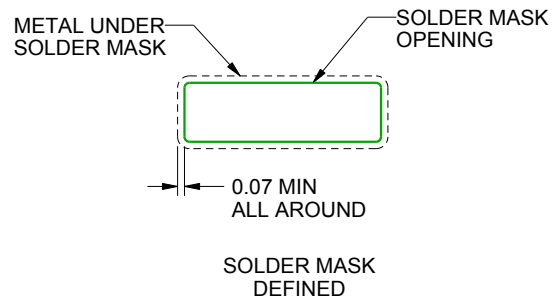
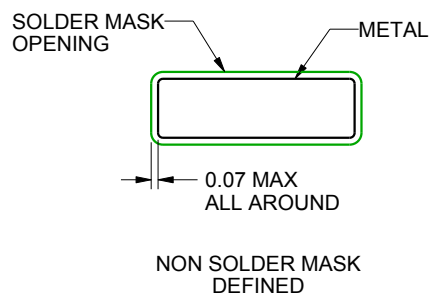
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

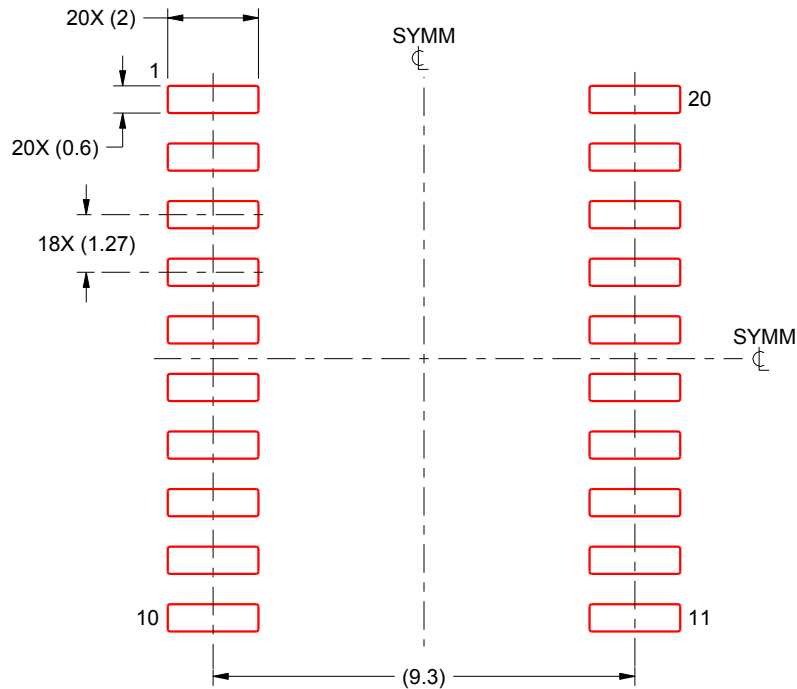
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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